



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260721000.1	PCN Issued	July 22, 2026
Qualification of additional Assembly sites for select package device		Sample request deadline:	September 20, 2026
		Estimated 1st ship date:	October 20, 2026
Sample requests received after September 20, 2026 will not be supported.			

Change type(s)
Assembly Site
Assembly Process
Assembly Material
Packing/Shipping/Labeling

PCN Details

Description of Change:																
Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction information and all assembly sites are as follows:																
<table><tr><th colspan="2">UxQFN Build sites</th></tr><tr><td>Assembly Sites</td><td>CARZ, CDAT, TIEMA, CLARK</td></tr><tr><td rowspan="2">Mold Compound</td><td>SID#441141</td></tr><tr><td>4222198</td></tr><tr><td rowspan="3">Mount Compound</td><td>SID#439825</td></tr><tr><td>SID#446422</td></tr><tr><td>4221460</td></tr><tr><td>Lead Frame Finish</td><td>NiPdAu</td></tr><tr><td>Bond Wire (mil)</td><td>Au (0.7 mil), Cu (0.8 mil)</td></tr></table>		UxQFN Build sites		Assembly Sites	CARZ, CDAT, TIEMA, CLARK	Mold Compound	SID#441141	4222198	Mount Compound	SID#439825	SID#446422	4221460	Lead Frame Finish	NiPdAu	Bond Wire (mil)	Au (0.7 mil), Cu (0.8 mil)
UxQFN Build sites																
Assembly Sites	CARZ, CDAT, TIEMA, CLARK															
Mold Compound	SID#441141															
	4222198															
Mount Compound	SID#439825															
	SID#446422															
	4221460															
Lead Frame Finish	NiPdAu															
Bond Wire (mil)	Au (0.7 mil), Cu (0.8 mil)															
Marking change:																
Marking difference	<table><tr><th>Current</th><th>Additional</th></tr><tr><td> * * M4 L * * L - Pin 1 based on Qtr Marked with 2 lines </td><td> * * M o * * o - Pin 1 Dot </td></tr></table>	Current	Additional	* * M4 L * * L - Pin 1 based on Qtr Marked with 2 lines	* * M o * * o - Pin 1 Dot											
Current	Additional															
* * M4 L * * L - Pin 1 based on Qtr Marked with 2 lines	* * M o * * o - Pin 1 Dot															
Qual details are provided in the Qual Data Section.																
Reason for Change:	Continuity of Supply															

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Physical aspects of the device have changed. Review the Standard Data Packet for more details on the changes			
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.			
	RoHS	REACH	Green	IEC 62474

	<table><tr><td colspan="2"></td><td colspan="2">Status</td></tr><tr><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td></tr></table>						Status		☒ No Change	☒ No Change	☒ No Change	☒ No Change
			Status									
☒ No Change	☒ No Change	☒ No Change	☒ No Change									
Changes to product identification resulting from this PCN:	Assembly Site Information											
	Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City								
	CARZ	CSZ	CHN	Jiangsu								
	CDAT	CDA	CHN	Chengdu								
	TIEM	CU6	MYS	Melaka								
	CLARK	QAB	PHL	Angeles City, Pampanga								
	Sample product shipping label (not actual product label):											
	<table><tr><td> TEXAS INSTRUMENTS MADE IN: China ZDC: 2Q MSL 1 / 260C / UNLIM OPT: ITEM: 73 LBL: 1A (L)T0:1168</td><td>  SEAL DT 04/14/17</td><td></td><td>(1P) PTAS2560YFFR (Q) 3000 (D) 1710 (31T) LOT: 7133710JCP (4W) SWR (1T) 2855550Z9A (P) (2P) REV: AO (V) 0033317 (20L) CSO: DM6 (21L) CCO: USA (22L) ASO: JCP (23L) ACO: CHN</td></tr></table>				 TEXAS INSTRUMENTS MADE IN: China ZDC: 2Q MSL 1 / 260C / UNLIM OPT: ITEM: 73 LBL: 1A (L)T0:1168	  SEAL DT 04/14/17		(1P) PTAS2560YFFR (Q) 3000 (D) 1710 (31T) LOT: 7133710JCP (4W) SWR (1T) 2855550Z9A (P) (2P) REV: AO (V) 0033317 (20L) CSO: DM6 (21L) CCO: USA (22L) ASO: JCP (23L) ACO: CHN				
	 TEXAS INSTRUMENTS MADE IN: China ZDC: 2Q MSL 1 / 260C / UNLIM OPT: ITEM: 73 LBL: 1A (L)T0:1168	  SEAL DT 04/14/17		(1P) PTAS2560YFFR (Q) 3000 (D) 1710 (31T) LOT: 7133710JCP (4W) SWR (1T) 2855550Z9A (P) (2P) REV: AO (V) 0033317 (20L) CSO: DM6 (21L) CCO: USA (22L) ASO: JCP (23L) ACO: CHN								

Products Affected:

SN74LVC1G08DPWR



TI Information
Selective Disclosure

UxQFN Qualification Report

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	CLARK SN74AXC2T45DTM LSF0102DTM LSF0002DTQ LSF0101DTQ	CDAT TLV70728PDQN TPL0102-100RUC 2N7001TDPWR
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/225/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/229/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	CARZ TPD4E101DPW TPS3700RUG	TIEMA LM43112SN LP8549B1ASPX03 LP3971SQ-D510/NOPB DS99R421ISNG2G
TC	Temperature Cycling -65/150C Or Temperature Cycling -55/125C	500 Cycles Or 700 Cycles	3/231/0	3/231/0
HAST/ THB	Biased HAST 130C/85%RH Or Biased HAST 110C/85%RH Or Temperature Humidity Bias, 85C/85%RH	96 hours Or 264 hours Or 1000 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C Or High Temp. Storage Bake 170C	1000 hours Or 420 hours	3/231/0	3/231/0
UHAST /AC	Unbiased HAST, 130C/85%RH Or Autoclave 121C	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

DRV5032DUDMR, DRV5032FADMR, TLV70728PDQN, TPD4E101DPW, TPL0102-100RUC, BQ298000RUG, TPS3700RUG, and TLV342IRUGR, PCA9306DQE, TPD4E6B06DPW, TCA6507RUE, DRV5032FDDMR, 2N7001TDPWR are qualified at L1-260C MSL rating

TLV9064IRUC qualified at L2-260C MSL rating

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable

- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/Green/Pb-free> Status: Qualified Pb-Free (SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.